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Part Number: [0717640022](#)
Status: **Active**
Description: 2.54mm (.100") Pitch C-Grid® Breakaway Header, Low Profile, Dual Row, Right Angle, High Temperature, 22 Circuits, Tin (Sn) Plating

Documents:

3D Model	Product Specification PS-71764 (PDF)
Packaging Specification (PDF)	RoHS Certificate of Compliance (PDF)
Drawing (PDF)	

Agency Certification

CSA	LR19980
UL	E29179

General

Product Family	PCB Headers
Series	71764
Application	Board-to-Board, Wire-to-Board
Product Name	C-Grid®

Physical

Breakaway	Yes
Circuits (Loaded)	22
Circuits (maximum)	22
Durability (mating cycles max)	25
Flammability	94V-0
Glow-Wire Compliant	No
Lock to Mating Part	None
Material - Metal	Brass, Phosphor Bronze
Material - Plating Mating	Tin
Material - Plating Termination	Tin
Number of Rows	2
Orientation	Right Angle
PC Tail Length (in)	0.110 In
PC Tail Length (mm)	2.79 mm
PCB Locator	No
PCB Retention	None
Packaging Type	Tube
Pitch - Mating Interface (in)	0.100 In
Pitch - Mating Interface (mm)	2.54 mm
Plating min: Mating (µin)	150
Plating min: Mating (µm)	3.75
Plating min: Termination (µin)	150
Plating min: Termination (µm)	3.75
Polarized to Mating Part	No
Shrouded	No
Stackable	Yes
Temperature Range - Operating	-40°C to +105°C
Termination Interface: Style	Through Hole

Electrical

Current - Maximum per Contact	3A
Voltage - Maximum	250V

Material Info

Reference - Drawing Numbers

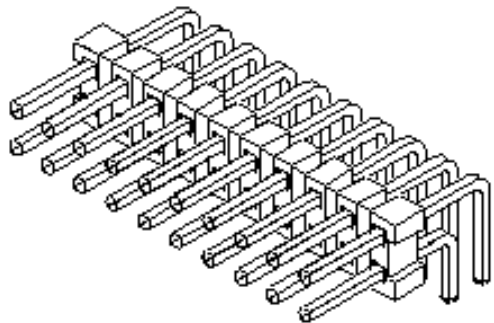


image - Reference only

Series

EU RoHS

**ELV and RoHS
Compliant**

REACH SVHC

Not Reviewed

Halogen-Free

Status

Not Reviewed

China RoHS



**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

Search Parts in this Series

[71764Series](#)

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J

I

H

G

F

E

D

C

B

A

13

12

11

10

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6

5

4

3

2

1

CKTS

DM. A

DM. B

04 (5.08)/.200 (2.54)/.100

06 (7.62)/.300 (5.08)/.200

08 (10.16)/.400 (7.62)/.300

10 (12.70)/.500 (10.16)/.400

12 (15.24)/.600 (12.70)/.500

14 (17.78)/.700 (15.24)/.600

16 (20.32)/.800 (17.78)/.700

18 (22.86)/.900 (20.32)/.800

20 (25.40)/1.000 (22.86)/.900

22 (27.94)/1.100 (25.40)/1.000

24 (30.48)/1.200 (27.94)/1.100

26 (33.02)/1.300 (30.48)/1.200

28 (35.56)/1.400 (33.02)/1.300

30 (38.10)/1.500 (35.56)/1.400

(2.29)
.090 REF.

BANDOLIER PIN
(0.64)/.025 SQUARE

2.54 ± 0.05
.100 ± .002 TYP.
(NON-ACCUM.)

2.54 ± 0.05
.100 ± .002

Ø 1.14 ± 0.05
.045 ± .002 TYP.

RECOMMENDED P.C. BOARD HOLE LAYOUT

DIM. A REF.

DIM. B REF.

CKT. 3

CKT. 5

CKT. 7

(1.27) REF.
.050

CKT. 1

(5.08)
.200 REF.

(2.54)
.100

(1.27)
.050 REF.

CKT. 8

CKT. 6

CKT. 4

CKT. 2

C ± (0.25)
.010

(2.54)
.100 SEE NOTE 8

E REF.

(2.29)
.090 REF.

(2.54)
.100 REF.

(1.27)
.050 SEE NOTE 8

NOTES:

1. MATERIAL: WAFER - HIGH TEMPERAURE THERMAL PLASTIC, 94V-0; COLOR: BLACK
PIN - COPPER ALLOY

2. PLATING:
TIN - (0.00381)/.000150 MINIMUM TIN PLATE OVER NICKEL PLATE.
15 GOLD - (0.00038)/.000015 MINIMUM GOLD PLATE IN SELECT AREA,
(0.00191)/.000075 MINIMUM TIN PLATE IN SELECT AREA,
OVER NICKEL PLATE OVERALL.
30 GOLD - (0.00076)/.000030 MINIMUM GOLD PLATE IN SELECT AREA,
(0.00191)/.000075 MINIMUM TIN PLATE IN SELECT AREA,
OVER NICKEL PLATE OVERALL.

* THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.

3. PRODUCT CONFORMS TO PS-71764.

4. PACKAGING INFORMATION:
FOR 4 THRU 8 CIRCUIT PARTS USE PK-70873-0353
FOR 10 CIRCUITS AND OVER USE PK-70873-0075

5. FOR ILLUSTRATION PURPOSES, 20 (DUAL 10) CIRCUIT SIZE IS SHOWN.

6. PINS MUST MEET SOLDERABILITY SPEC. ES-152, EXCEPT VOIDS ARE PERMISSIBLE AT BANDOLIER PIN AT BANDOLIER PIN FAYING SURFACE.
(APPROX. (0.64)/.025 LNG X (0.15)/.006 WD. REF.) 2 LOCATIONS

7. WAFER TO BE FLAT WITHIN (0.03 MM/CM) OR .003 IN./IN

8. MEASURE POINT FOR PLATING THICKNESS.

9. THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002

ADD NOTE 9

EC NO: UCP2007-1441

DRWN/PRI DDER 2006/12/11

CHK'D/ADR 2006/12/11

APP'R/FSL TH 2006/12/12

DESCRIPTION

QUALITY SYMBOLS

GENERAL TOLERANCES (UNLESS SPECIFIED)

MM

INCH

4 PLACES ± --- ± ---

3 PLACES ± --- ± .01

2 PLACES ± 0.25 ± .01

1 PLACE ± 0.25 ± ---

ANGULAR ± 1/2°

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE MM/IN

SCALE 4:1

DESIGN UNITS INCH

THIRD ANGLE PROJECTION

DRAWN BY DATE CAC 1995/08/23

CHECKED BY DATE PR 1995/08/23

APPROVED BY DATE DJB 1995/08/23

MATERIAL NO.

SHEET NO. 1 OF *

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

SEE TABLE

SD-71764-001

MOLEX INCORPORATED

DUAL ROW WAFER ASS'Y W/BREAK-OFF OPTION RT. ANG. (0.64)/.025 SQ PINS

12

11

10

9

8

7

6

5

4

3

2

1

ITEM NO: 71764-0004/0030, 9003			ITEM NO: 71764-0104/0130, 9001, 9004			ITEM NO: 71764-0204/0230, 9000, 9002		
DIM. C		(6.10)/.240	DIM. C		(6.10)/.240	DIM. C		(6.10)/.240
DIM. E (REF.)		(2.79)/.110	DIM. E (REF.)		(2.79)/.110	DIM. E (REF.)		(2.79)/.110
FINISH		TIN	FINISH		15 GOLD	PLATING FINISH		30 GOLD
CONNECTOR END PLATING		TIN	CONNECTOR END PLATING		GOLD	CONNECTOR END PLATING		GOLD
P.C. BOARD END PLATING		TIN	P.C. BOARD END PLATING		TIN	P.C. BOARD END PLATING		TIN
PACKAGING		SEE NOTE 4 SHEET 1	PACKAGING		SEE NOTE 4 SHEET 1	PACKAGING		SEE NOTE 4 SHEET 1
CKTS	ITEM NUMBER	VOIDS	CKTS	ITEM NUMBER	VOIDS	CKTS	ITEM NUMBER	VOIDS
04	71764-0004		04	71764-0104		04	71764-0204	
06	71764-0006		06	71764-0106		06	71764-0206	
08	71764-0008		08	71764-0108		08	71764-0208	
10	71764-0010		10	71764-0110		10	71764-0210	
12	71764-0012		12	71764-0112		12	71764-0212	
14	71764-0014		14	71764-0114		14	71764-0214	
16	71764-0016		16	71764-0116		16	71764-0216	
18	71764-0018		18	71764-0118		18	71764-0218	
20	71764-0020		20	71764-0120		20	71764-0220	
22	71764-0022		22	71764-0122		22	71764-0222	
24	71764-0024		24	71764-0124		24	71764-0224	
26	71764-0026		26	71764-0126		26	71764-0226	
28	71764-0028		28	71764-0128		28	71764-0228	
30	71764-0030		30	71764-0130		30	71764-0230	
06	71764-9003	3	06	71764-9001	3, 4	06	71764-9002	3, 4
			08	71764-9004	5, 6			
						10	71764-9000	8

REV: A	<u>ECR/ECN INFORMATION</u>		<u>TITLE:</u> DUAL ROW WAFER ASS'Y W/ BREAK-OFF OPTION RT. ANG. (0.64)/.025 SQ PINS			<u>SHEET No.</u> - 2 -		
	<u>EC No:</u> UCP2007-0449							
	<u>DATE:</u> 2006-08-18							
<u>DOCUMENT NUMBER:</u> SD-71764-001			<u>CREATED / REVISED BY:</u> PRIDDER		<u>CHECKED BY:</u> ADERR		<u>APPROVED BY:</u> FSMITH	

ITEM NO: 71764-0304/0330			ITEM NO: 71764-0404/0430			ITEM NO: 71764-0504/0530		
DIM. C		(8.13)/.320	DIM. C		(8.13)/.320	DIM. C		(8.13)/.320
DIM. E (REF.)		(2.79)/.110	DIM. E (REF.)		(2.79)/.110	DIM. E (REF.)		(2.79)/.110
PLATING FINISH		TIN	PLATING FINISH		15 GOLD	PLATING FINISH		30 GOLD
CONNECTOR END PLATING		TIN	CONNECTOR END PLATING		GOLD	CONNECTOR END PLATING		GOLD
P.C. BOARD END PLATING		TIN	P.C. BOARD END PLATING		TIN	P.C. BOARD END PLATING		TIN
PACKAGING		SEE NOTE 4 SHEET 1	PACKAGING		SEE NOTE 4 SHEET 1	PACKAGING		SEE NOTE 4 SHEET 1
CKTS	ITEM NUMBER	VOIDS	CKTS	ITEM NUMBER	VOIDS	CKTS	ITEM NUMBER	VOIDS
04	71764-0304		04	71764-0404		04	71764-0504	
06	71764-0306		06	71764-0406		06	71764-0506	
08	71764-0308		08	71764-0408		08	71764-0508	
10	71764-0310		10	71764-0410		10	71764-0510	
12	71764-0312		12	71764-0412		12	71764-0512	
14	71764-0314		14	71764-0414		14	71764-0514	
16	71764-0316		16	71764-0416		16	71764-0516	
18	71764-0318		18	71764-0418		18	71764-0518	
20	71764-0320		20	71764-0420		20	71764-0520	
22	71764-0322		22	71764-0422		22	71764-0522	
24	71764-0324		24	71764-0424		24	71764-0524	
26	71764-0326		26	71764-0426		26	71764-0526	
28	71764-0328		28	71764-0428		28	71764-0528	
30	71764-0330		30	71764-0430		30	71764-0530	

REV: A	<u>ECR/ECN INFORMATION</u>		<u>TITLE:</u> DUAL ROW WAFER ASS'Y W/ BREAK-OFF OPTION RT. ANG. (0.64)/.025 SQ PINS			<u>SHEET No.</u> - 3 -		
	<u>EC No:</u> UCP2007-0449							
	<u>DATE:</u> 2006-08-18							
<u>DOCUMENT NUMBER:</u> SD-71764-001			<u>CREATED / REVISED BY:</u> PRIDDER		<u>CHECKED BY:</u> ADERR		<u>APPROVED BY:</u> FSMITH	